IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.:	10/789,914				
Filing Date:	February 27, 2004				
Applicant:	Hosomi et al.				
Group Art Unit:	1714				
Examiner:	Kriellion Sanders				
Title:	Resin Semicon	Composition, ductor Package	Prepeg,	Laminate	and
Attorney Docket:	2497-000002/CP				
Commissioner for P.O. Box 1450 Alexandria, Virginia	a 22313-1	450 ENDMENT UNDE	:R 37 CFR 1	⊥ <u>.312</u>	
Sir:				<u></u>	
After the No	otice of Al	lowance dated Ju	une 27, 200	7 and before	payment of the
issue fee, please	amend the	application as fo	ollows and c	consider the re	emarks set forth
below.					
Please consider the	e following	:			

☐ Amendments to the Abstract;

☐ Amendments to the Claims;.

⊠ Remarks